Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

      1.   (Previously presented) A method for determining an operating parameter of a chip having first and second ring oscillators, comprising:

            measuring a frequency of the first ring oscillator;

            measuring a frequency of the second ring oscillator; and

            calculating an actual temperature of the chip as a function of the first and second ring oscillator frequencies.

      2.   (Original)   The method of claim 1 wherein the measuring of the first ring oscillator frequency comprises:

            obtaining two ring oscillator clock counts, separated by a time difference, from a ring oscillator;

            obtaining two independent clock counts, separated by the time differences, from a clock output independent from the ring oscillator; and

            calculating a ratio of the difference between the two ring oscillator clock values and the difference between the two independent clock values.

      3.   Canceled.

      4.   Canceled.

      5.   (Previously presented) The method of claim 1, further comprising:

            multiplying the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a result; and

determining, as a function of the result and characterization data of the chip, the chip's actual temperature.

6.   (Previously presented) The method of claim 33, further comprising:

dividing the measured frequency of the first ring oscillator frequency by the measured frequency of the second ring oscillator to obtain a result; and

determining, as a function of the result and characterization data of the chip, the chip's process speed.

7.   (Previously presented) The method of claim 6, further comprising:

multiplying the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a second result;

determining, as a function of the second result and the characterization data, the chip's actual temperature; and

adjusting the determined process speed according to the determined actual temperature.

8.   (Previously presented) The method of claim 1, further comprising:

calculating a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

comparing the calculated scaled frequency value with a known range of scaled frequency values relative to temperature; and

determining, from the comparison, the actual temperature of the chip.

9.   (Previously presented) The method of claim 33, further comprising:

calculating a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

comparing the calculated scaled frequency value with a known range of scaled frequency numbers relative to process speed; and

determining, from the comparison, the process speed of the chip.

10.   (Previously presented) Computer-readable media embodying a program of instructions executable by a computer to perform a method of determining an operating parameter of a chip having first and second ring oscillators, the method comprising:

measuring a frequency of the first ring oscillator;

measuring a frequency of the second ring oscillator; and

calculating an actual temperature of the chip as a function of the first and second ring oscillator frequencies.

11.   (Original) The computer-readable media of claim 10 wherein the measuring of the first ring oscillator frequency comprises:

obtaining two ring oscillator clock counts, separated by a time difference, from a ring oscillator;

obtaining two independent clock counts, separated by the time difference, from a clock output independent of the ring oscillator; and

calculating a ratio of the difference between the two ring oscillator clock values and the difference between the two independent clock values.

12.   Canceled.

13.   Canceled.

14.   (Previously presented) The computer-readable media of claim 10, wherein the method further comprises:

multiplying the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a result; and

determining, as a function of the result and characterization data of the chip, the chip's actual temperature.

15.   (Previously presented) The computer-readable media of claim 34, wherein the method further comprises:

dividing the measured frequency of the first ring oscillator frequency by the measured frequency of the second ring oscillator to obtain a result; and

determining, as a function of the result and characterization data of the chip, the chip's process speed.

16.   (Previously presented) The computer-readable media of claim 15, wherein the method further comprises:

multiplying the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a second result;

determining, as a function of the second result and the characterization data, the chip's actual temperature; and

adjusting the determined process speed according to the determined actual temperature.

17.   (Previously presented) The computer-readable media of claim 10, wherein the method further comprises:

calculating a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

comparing the calculated scaled frequency value with a known range of scaled frequency values relative to temperature; and

determining, from the comparison, the actual temperature of the chip.

18.   (Previously presented) The computer-readable media of claim 34, wherein the method of further comprises:

calculating a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

comparing the calculated scaled frequency value with a known range of scaled frequency numbers relative to process speed; and

determining, from the comparison, the process speed of the chip.

19.   (Previously presented) A system comprising:

a chip having first and second ring oscillators; and

a processor configured to:

measure a frequency of the first ring oscillator;

measure a frequency of the second ring oscillator; and

calculate an actual temperature of the chip as a function of the first and second ring oscillator frequencies.

20.   (Original) The system of claim 19 wherein the chip comprises the processor.

21.   (Original) The system of claim 19 wherein the processor is separate from but operably connected to the chip.

22.   (Original) The system of claim 19 wherein the chip additionally comprises:

a first counter configured to obtain two ring oscillator clock counts, separated by a time difference, from the first ring oscillator;

a second counter configured to obtain two independent clock counts, separated by the time difference, from a clock output independent of the first and second ring oscillators; and

wherein the processor is further configured to calculate a ratio of the difference between the two ring oscillator clock values and the difference between the two independent clock values.

23.   Canceled.

24.   Canceled.

25.   (Previously presented)   The system of claim 19, wherein the processor is additionally configured to:

multiply the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a result; and

determine, as a function of the result and characterization data of the chip, the chip's actual temperature.

26.   (Previously presented)   The system of claim 35, wherein the processor is additionally configured to:

divide the measured frequency of the first ring oscillator frequency by the measured frequency of the second ring oscillator to obtain a result; and

determine, as a function of the result and characterization data of the chip, the chip's process speed.

27.   (Previously presented) The system of claim 26, wherein the processor is further configured to:

multiply the measured frequency of the first ring oscillator by the measured frequency of the second ring oscillator to obtain a second result;

determine, as a function of the second result and the characterization data, the chip's actual temperature; and

adjust the determined process speed according to the determined actual temperature.

28.   (Previously presented) The system of claim 19, wherein the processor is further configured to:

calculate a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

compare the calculated scaled frequency value with a known range of scaled frequency values relative to temperature; and

determine, from the comparison, the actual temperature of the chip.

29.   (Previously presented) The system of claim 35, wherein the processor is further configured to:

calculate a scaled frequency value from the first and second measured ring oscillator frequencies and characterization data of the chip;

compare the calculated scaled frequency value with a known rang of scaled frequency numbers relative to process speed; and

determine, from the comparison, the process speed of the chip.

30.   (Previously presented) A processor comprising:

means for measuring a frequency of a first ring oscillator;

means for measuring a frequency of the second ring oscillator; and

means for calculating an actual temperature of a chip as a function of the first and second ring oscillator frequencies.

31.   Canceled.

32.   Canceled.

33.   (Previously presented) The method of claim 1 further comprising determining a process speed of the chip in response to the actual temperature.

34.   (Currently amended)   The ~~method~~ media of claim 10 further comprising determining a process speed of the chip in response to the actual temperature.

35.   (Currently amended) The ~~method~~ system of claim 19 wherein the processor is further configured to determine a process speed of the chip in response to the actual temperature.

36.   (Currently amended) The ~~method~~ processor of claim 30 further comprising means for determining a process speed of the chip in response to the actual temperature.